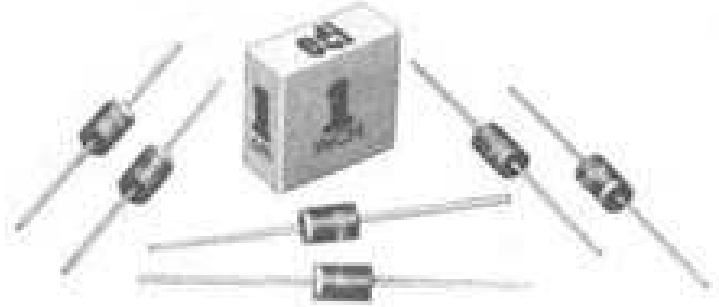




3W 3RW

HIGH VOLTAGE, HIGH CURRENT, FAST RECOVERY SILICON RECTIFIER DIODES

- Up to 250 ns max. recovery
- Small size
- Exceptionally low leakage
- Avalanche characteristics



EDI Type	PRV Volts	REVERSE RECOVERY TIME (Fig.4)
3W2	2,000	Not applicable
3W2.5	2,500	Not applicable
3W3	3,000	Not applicable
3RW2	2,000	250 ns max.
3RW2.5	2,500	250 ns max.
3RW3	3,000	250 ns max.

ELECTRICAL CHARACTERISTICS(at $T_A=25^{\circ}\text{C}$ Unless Otherwise Specified)

ELECTRICAL CHARACTERISTICS	3W	3RW
Average Rectified Forward Current @ 50°C , I_o (Fig.1)	2 Amp	1.5 Amp
Max. Peak Surge Current, I_{FSM} (8.3 ms) (Fig.2)	300 Amp	200 Amp
Max. Forward Voltage Drop @ 2.0 A, V_F	3VDC max.	4VDC max.
Max. DC Reverse Current @ PRV and 25°C , I_R	5 μA	10 μA
Max. DC Reverse Current @ PRV and 100°C , I_R	150 μA	200 μA
Ambient Operating Temperature Range, T_A	-55°C to $+150^{\circ}\text{C}$	-55°C to $+125^{\circ}\text{C}$
Storage Temperature Range, T_{STG}	-55°C to $+150^{\circ}\text{C}$	

NOTES: It is recommended that a proper heat sink be used on the terminals of this device between the body and soldering point to prevent damage from excess heat.

Maximum lead and terminal temperature for soldering, 3/8 inch from case, 5 seconds at 250°C

EDI reserves the right to change these specifications at any time without notice.

FIG.1
OUTPUT CURRENT vs AMBIENT TEMPERATURE

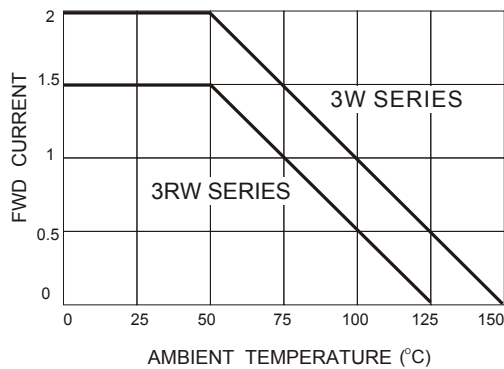


FIG.2
NON-REPETITIVE SURGE CURRENT

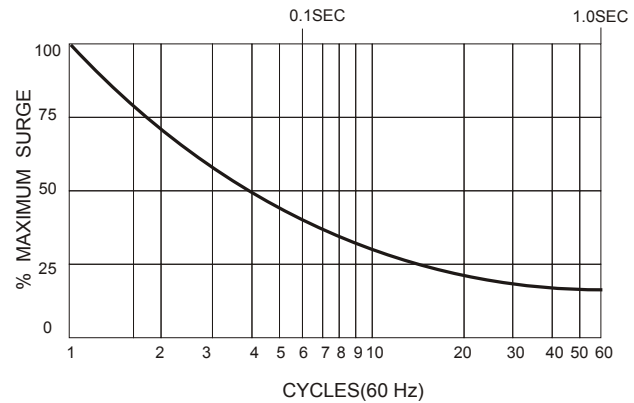
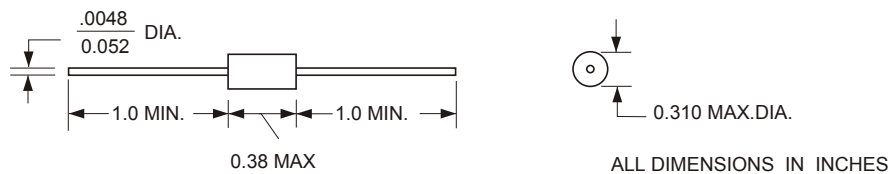


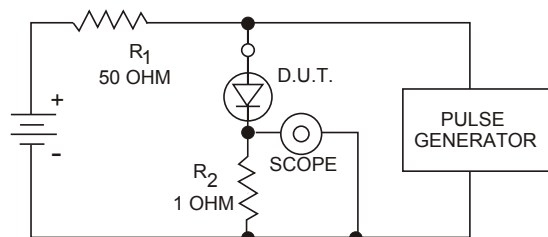
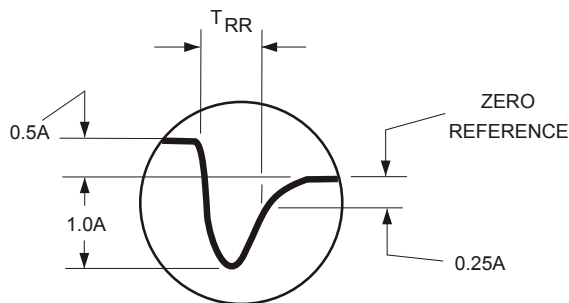
FIG.3



NOTE Maximum lead and terminal temperature for soldering, 3/8 inch form case, 5 seconds at 250 °C

TEST CIRCUIT
FIG.4

TYPICAL REVERSE RECOVERY WAVEFORM



R_1, R_2 NON-INDUCTIVE RESISTORS
PULSE GENERATOR-HEWLETT PACKARD 214A OR EQUIV.
IKC REP.RATE, 10μ SEC. PULSE WIDTH
ADJUST PULSE AMPLITUDE FOR PEAK I_R